NPN-Silizium-Fototransistor
Silicon NPN Phototransistor

SFH 302

Wesentliche Merkmale

- Speziell geeignet für Anwendungen im Bereich von 450 nm bis 1100 nm
- Hohe Linearität
- TO-18, Bodenplatte, klares Epoxy-Gießharz, mit Basisanschluß
- Gruppiert lieferbar

Features

- Especially suitable for applications from 450 nm to 1100 nm
- High linearity
- TO-18, base plate, transparent exposy resin lens, with base connection
- Available in groups

Anwendungen

- Lichtschranken für Gleich- und Wechsellichtbetrieb
- Industrieelektronik
- „Messen/Steuern/Regeln“

Applications

- Photointerrupters
- Industrial electronics
- For control and drive circuits

Typ Type	Bestellnummer Ordering Code
SFH 302	Q62702-P1641

Grenzwerte
Maximum Ratings

Bezeichnung **Parameter**	**Symbol** **Symbol**	**Wert** **Value**	**Einheit** **Unit**
Betriebs- und Lagertemperatur Operating and storage temperature range	T_{op}; T_{stg}	– 40 … + 80	°C
Löttemperatur bei Tauchlötung Lötstelle ≥ 2 mm vom Gehäuse, Lötzeit $t \leq 5$ s Dip soldering temperature ≥ 2 mm distance from case bottom, soldering time $t \leq 5$ s	T_S	260	°C
Löttemperatur bei Kolbenlötung Lötstelle ≥ 2 mm vom Gehäuse, Lötzeit $t \leq 3$ s Iron soldering temperature ≥ 2 mm distance from case bottom, soldering time $t \leq 3$ s	T_S	300	°C
Kollektor-Emitterspannung Collector-emitter voltage	V_{CE}	50	V
Kollektorstrom Collector current	I_C	50	mA
Kollektorspitzenstrom, $\tau < 10$ µs Collector surge current	I_{CS}	200	mA
Emitter-Basisspannung Emitter-base voltage	V_{EB}	7	V
Verlustleistung, $T_A = 25$ °C Total power dissipation	P_{tot}	150	mW
Wärmewiderstand Thermal resistance	R_{thJA}	450	K/W

Kennwerte (T_A = 25 °C, λ = 950 nm)
Characteristics

Bezeichnung **Parameter**	**Symbol** **Symbol**	**Wert** **Value**	**Einheit** **Unit**
Wellenlänge der max. Fotoempfindlichkeit Wavelength of max. sensitivity	$\lambda_{S\ max}$	880	nm
Spektraler Bereich der Fotoempfindlichkeit S = 10% von S_{max} Spectral range of sensitivity S = 10% of S_{max}	λ	450 … 1100	nm
Bestrahlungsempfindliche Fläche Radiant sensitive area	A	0.675	mm^2
Abmessungen der Chipfläche Dimensions of chip area	$L \times B$ $L \times W$	1 × 1	mm × mm
Abstand Chipoberfläche zu Gehäuseoberfläche Distance chip front to case surface	H	0.2 … 0.8	mm
Halbwinkel Half angle	φ	± 50	Grad deg.
Fotostrom der Kollektor-Basis-Fotodiode Photocurrent of collector-base photodiode E_e = 0.5 mW/cm², V_{CB} = 5 V E_v = 1000 lx, Normlicht/standard light A, V_{CB} = 5 V	 I_{PCB} I_{PCB}	 4.2 12.5	 µA µA
Kapazität Capacitance V_{CE} = 0 V, f = 1 MHz, E = 0 V_{CB} = 0 V, f = 1 MHz, E = 0 V_{EB} = 0 V, f = 1 MHz, E = 0	 C_{CE} C_{CB} C_{EB}	 23 39 47	 pF pF pF
Dunkelstrom Dark current V_{CE} = 10 V, E = 0	I_{CEO}	20 (≤ 200)	nA

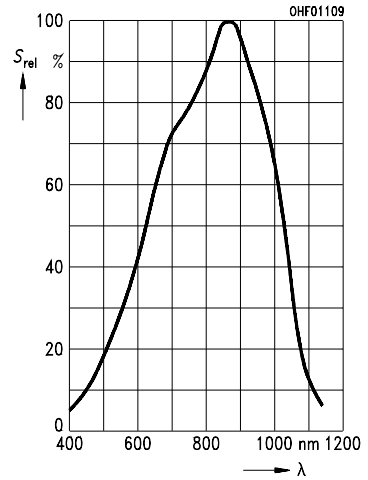
Die Fototransistoren werden nach ihrer Fotoempfindlichkeit gruppiert und mit arabischen Ziffern gekennzeichnet.
The phototransistors are grouped according to their spectral sensitivity and distinguished by arabian figures.

Bezeichnung Parameter	Symbol Symbol	Wert Value					Einheit Unit
		-2	-3	-4	-5	-6	
Fotostrom, $\lambda = 950$ nm Photocurrent E_e = 0.5 mW/cm², V_{CE} = 5 V E_v = 1000 lx, Normlicht/standard light A V_{CE} = 5 V	 I_{PCE} I_{PCE}	 0.4 … 0.8 1.75	 0.63 … 1.25 2.8	 1 … 2 4.5	 1.6 … 3.2 7.1	 ≥ 2.5 9.5	 mA mA
Anstiegszeit/Abfallzeit Rise and fall time I_C = 1 mA, V_{CC} = 5 V, R_L = 1 kΩ	t_r, t_f	9	11	14	17	20	µs
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage $I_C = I_{PCEmin}$ [1] × 0.3, E_e = 0.5 mW/cm²	V_{CEsat}	200	200	200	200	200	mV
Stromverstärkung Current gain E_e = 0.5 mW/cm², V_{CE} = 5 V	$\frac{I_{PCE}}{I_{PCB}}$	140	230	360	570	750	–

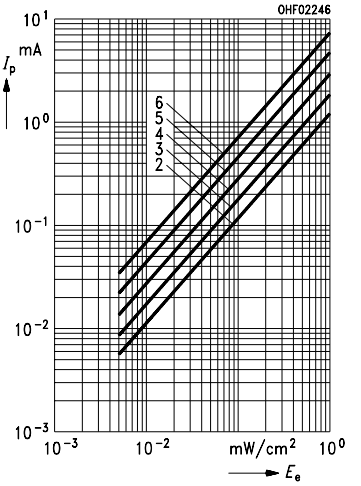
[1] I_{PCEmin} ist der minimale Fotostrom der jeweiligen Gruppe.

[1] I_{PCEmin} is the min. photocurrent of the specified group.

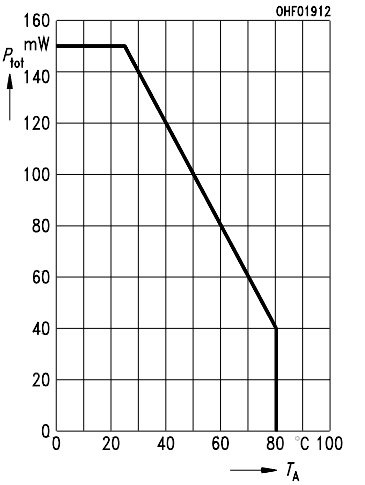
Relative Spectral Sensitivity
$S_{rel} = f(\lambda)$



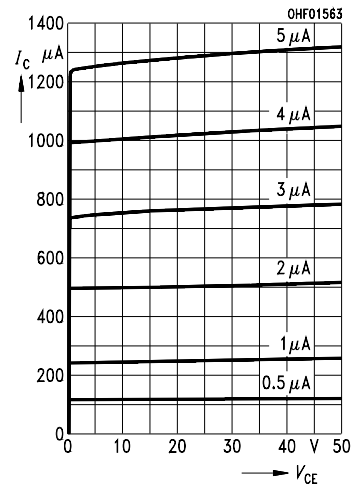
Photocurrent
$I_{PCE} = f(E_e)$, V_{CE} = 5 V



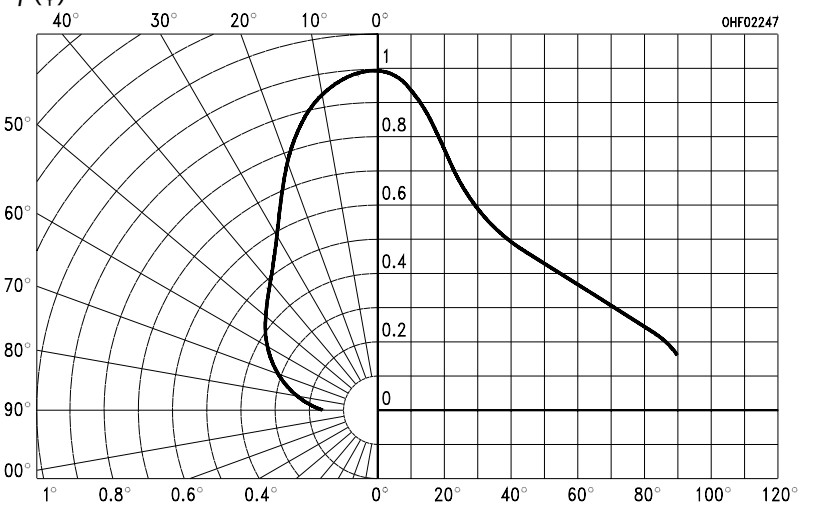
Total Power Dissipation
$P_{tot} = f(T_A)$



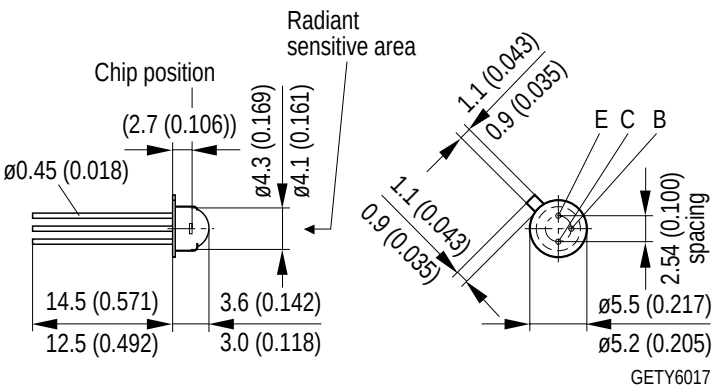
Output Characteristics
$I_C = f(V_{CE})$, I_B = Parameter



Directional Characteristics
$S_{rel} = f(\varphi)$



Maßzeichnung
Package Outlines



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

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